

## AMENDMENT TO SPECIFICATION

Please amend the first paragraph of the specification as follows:

The present disclosure relates to flexible circuits, and among[[st]] other things to improved cover layers for flexible circuits.

Please amend the following paragraph which begins on page 11 line 10 as follows:

One or more openings 325, 326 are formed in the substrate 310. In one embodiment, the openings 325, 326 are cut by any well-known in the art masked laser cutting or scanning laser cutting process, punching the substrate or etching the substrate. In one embodiment, the openings 325, 326 may be cut at the time of cutting other openings, such as the beam openings 322. The shape, size, location and/or number of openings 325, 326 are variables that may be changed to reduce de-bonding, wicking and/or the like for a particular application in which the flexible circuit is utilized. The shape, size, location and/or number of openings for example may be selected to provide the maximum area of encapsulation along the sides of the flexible circuit. The shape, size, location and/or number of openings for example may be selected to minimize sagging, buckling and/or the like of the roll of substrate when processing on the reel-to-reel equipment. Additionally, embodiments of the present invention are

200810509-1  
Examiner: Nguyen, Hoa Cao

2

Serial No.: 10/759,363  
Group Art Unit: 2841

also well suited to use with flexible circuits having integrated circuit (ICs) [[336]] and/or other active or passive components coupled thereto. Furthermore, embodiments of the present invention are also well suited to use with flexible circuits having integrated circuits (ICs) [[336]] and/or other active or passive components located on either the top and/or the bottom surface of the flexible circuit.

200310509-1  
Examiner: Nguyen, Hoa Cao

3

Serial No.: 10/759,363  
Group Art Unit: 2841